

COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

Abstract of the Disclosure

Dielectric materials comprising release agents are described. Also described
are a process for improving the processability of dielectric materials during hot
5 embossing, substrates prepared by hot embossing, and integrated-circuit packages
comprising the improved substrate.

"Express Mail" mailing label number: EV370238767US

Date of Deposit: December 31, 2003

This paper or fee is being deposited on the date indicated above with
the United States Postal Service pursuant to 37 CFR 1.10, and is
addressed to the Commissioner for Patents, Mail Stop Patent
Application, P.O. Box 1450, Alexandria, VA 22313-1450.